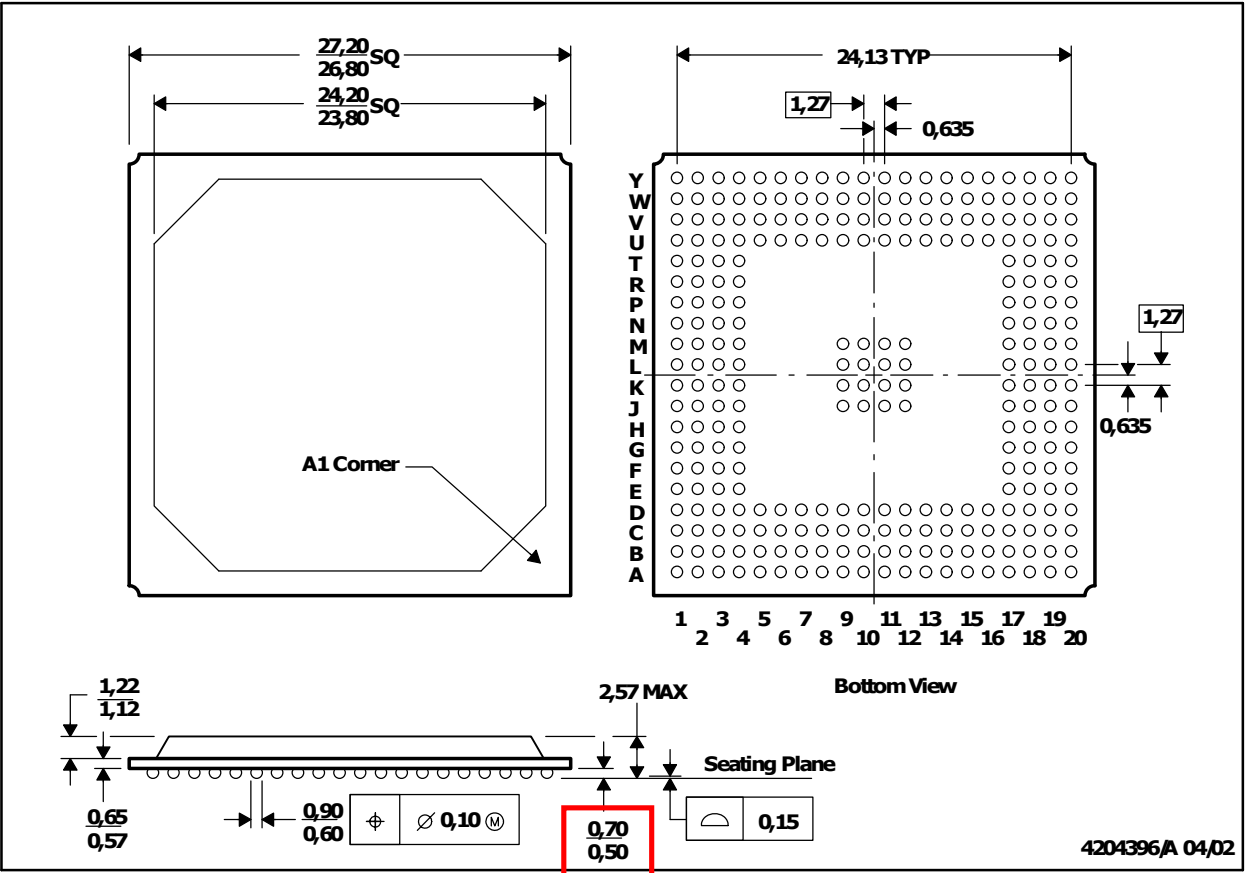


TMS320C6713, TMS320C6713B
FLOATING-POINT DIGITAL SIGNAL PROCESSORS

SPRS186I – DECEMBER 2001 – REVISED MAY 2004

MECHANICAL DATA
GDP (S-PBGA-N272) PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MO-151

thermal resistance characteristics (S-PBGA package)

NO		°C/W	Air Flow(m/s) [†]
Two Signals, Two Planes (4-Layer Board)			
1	R _{θJC} Junction-to-case	9.7	N/A
2	Ψ _{iJT} Junction-to-package top	1.5	0.0
3	R _{θJB} Junction-to-board	19	N/A
4	R _{θJA} Junction-to-free air	22	0.0
5	R _{θJA} Junction-to-free air	21	0.5
6	R _{θJA} Junction-to-free air	20	1.0
7	R _{θJA} Junction-to-free air	19	2.0
8	R _{θJA} Junction-to-free air	18	4.0
9	Ψ _{iJB} Junction-to-board	16	0.0

[†] m/s =meters per second